

Title (en)

IMPROVED CHEMICAL DRYING AND CLEANING SYSTEM

Title (de)

VERBESSERTES CHEMISCHES TROCKNUNGS- UND REINIGUNGSSYSTEM

Title (fr)

SYSTEME CHIMIQUE AMELIORE DE SECHAGE ET DE NETTOYAGE

Publication

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Application

EP 98948428 A 19980922

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- US 93567197 A 19970923
- US 3436998 A 19980303
- US 10946098 A 19980702

Abstract (en)

[origin: WO9915845A1] A system (11) for drying and/or cleaning a workpiece (17A), such as an electronic part, semiconductor wafer, printed circuit board or the like. As the workpiece is withdrawn from a processing or rinsing liquid (13), a selected drying and/or cleaning liquid, such as hydrofluoroether (HFE), an ethylated hydrofluoroether or an azeotrope of a hydrofluoroether or ethylated hydrofluoroether, that has a very small surface tension, is volatile, and has a density much greater than the processing liquid density, is sprayed on, dribbled on, or otherwise transferred to an exposed surface of the workpiece. The workpiece can be dried in 7-45 seconds, or less, in most situations and can be cleaned using the invention. Drying and/or cleaning can be performed in a single workpiece process, a single workpiece, continuous process, or a batch process.

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IPC 8 full level

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